

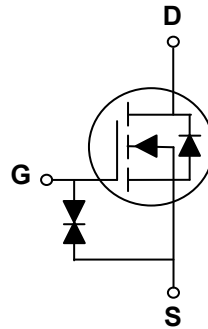
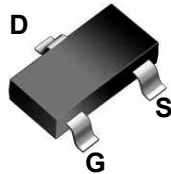
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	60V
I_D (at $V_{GS}=10V$)	0.3A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	1.7 Ω (Typ)
ESD protected	

SOT23



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	0.3
	TC=100 $^\circ\text{C}$	I_D	0.18
Drain Current – Pulsed	I_{DM}	1.2	A
Maximum Power Dissipation	P_D	0.35	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		80	$^\circ\text{C}/\text{W}$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		125	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	68		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =0.3A		1.7	2.5	Ω
		V _{GS} =4.5V, I _D =0.2A		1.9	3.0	Ω
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, F=1.0MHz		30	50	pF
C _{OSS}	Output Capacitance			5.5	12	pF
C _{RSS}	Reverse Transfer Capacitance			4	8	pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DD} =30V, I _D =0.2A, V _{GS} =10V, R _G =6Ω		3	7	nS
t _r	Turn-on Rise Time			5	11	nS
t _{d(off)}	Turn-Off Delay Time			14	30	nS
t _f	Turn-Off Fall Time			9	20	nS
Q _g	Total Gate Charge	V _{DS} =30V, I _D =0.2A, V _{GS} =10V		1.1	2.0	nC
Q _{gs}	Gate-Source Charge			0.1	1.0	nC
Q _{gd}	Gate-Drain Charge			0.23	1.0	nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A		0.70	1.4	V

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

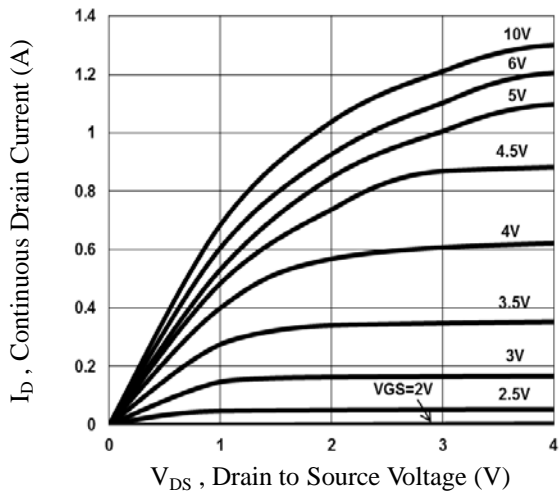


Fig.1 Output Characteristics

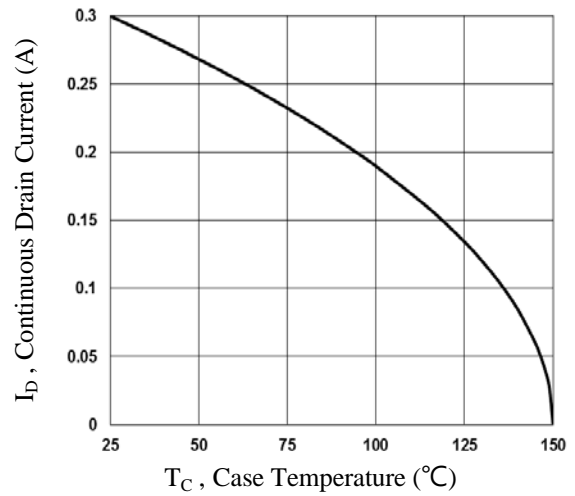


Fig.2 Continuous Drain Current vs. T_C

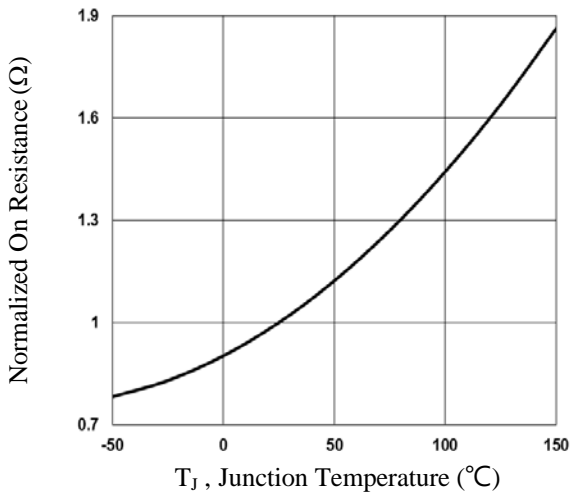


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

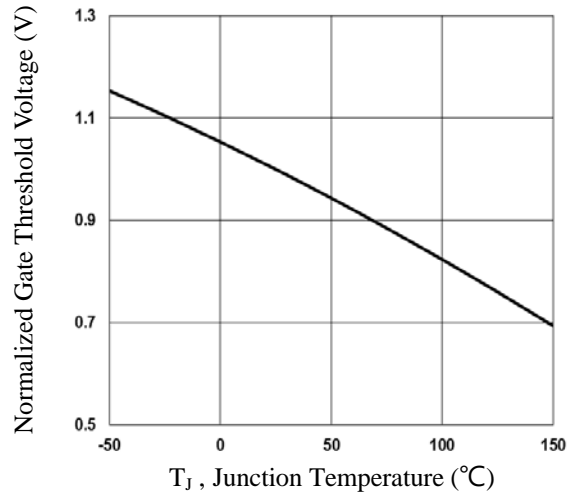


Fig.4 Normalized V_{th} vs. T_J

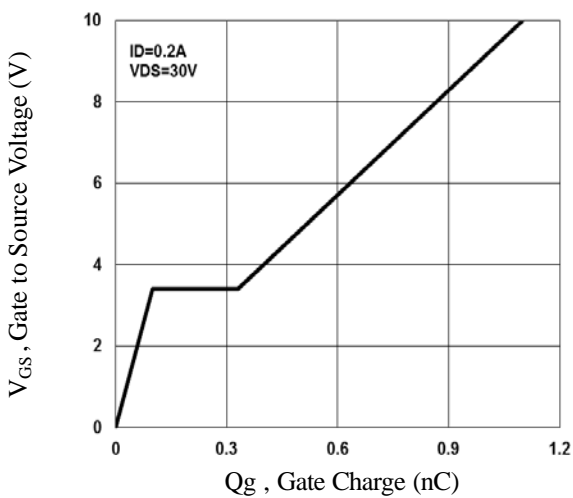


Fig.5 Gate Charge Waveform

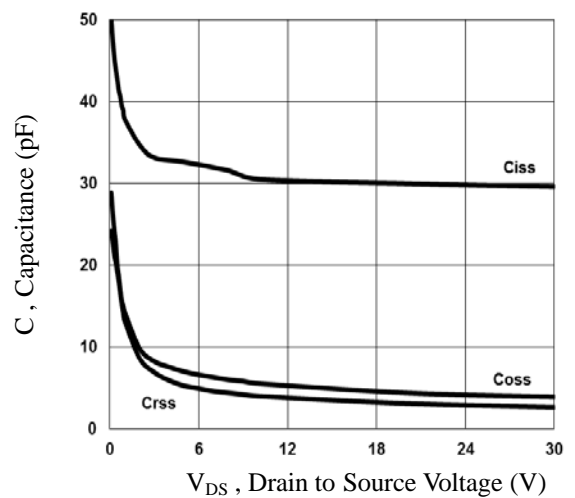


Fig.6 Capacitance Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

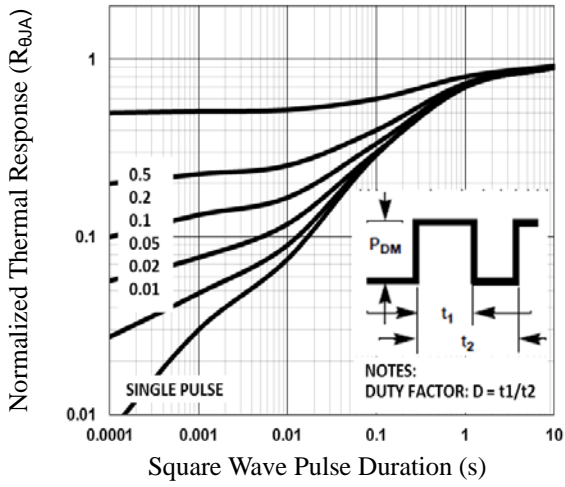


Fig.7 Normalized Transient Impedance

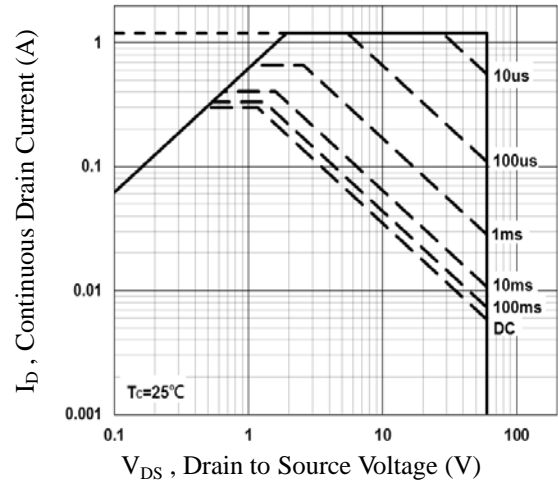


Fig.8 Maximum Safe Operation Area

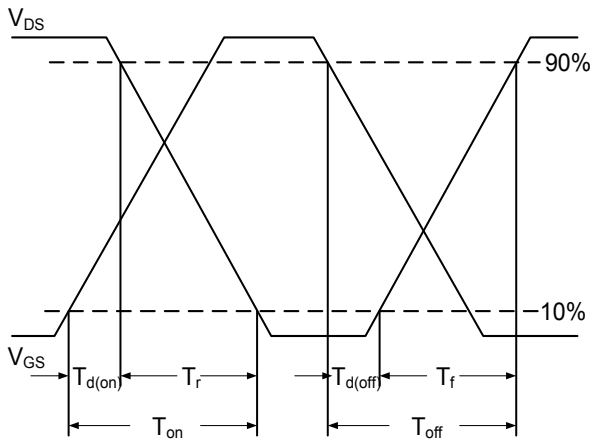


Fig.9 Switching Time Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

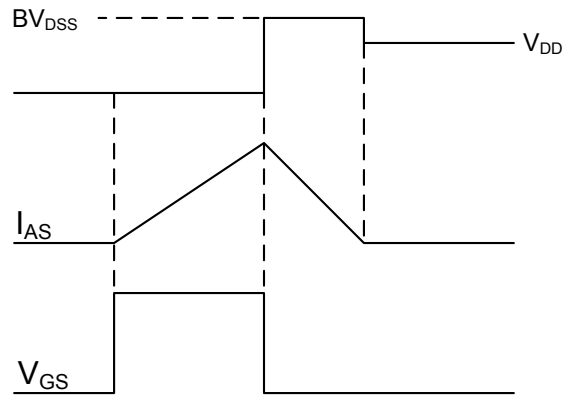
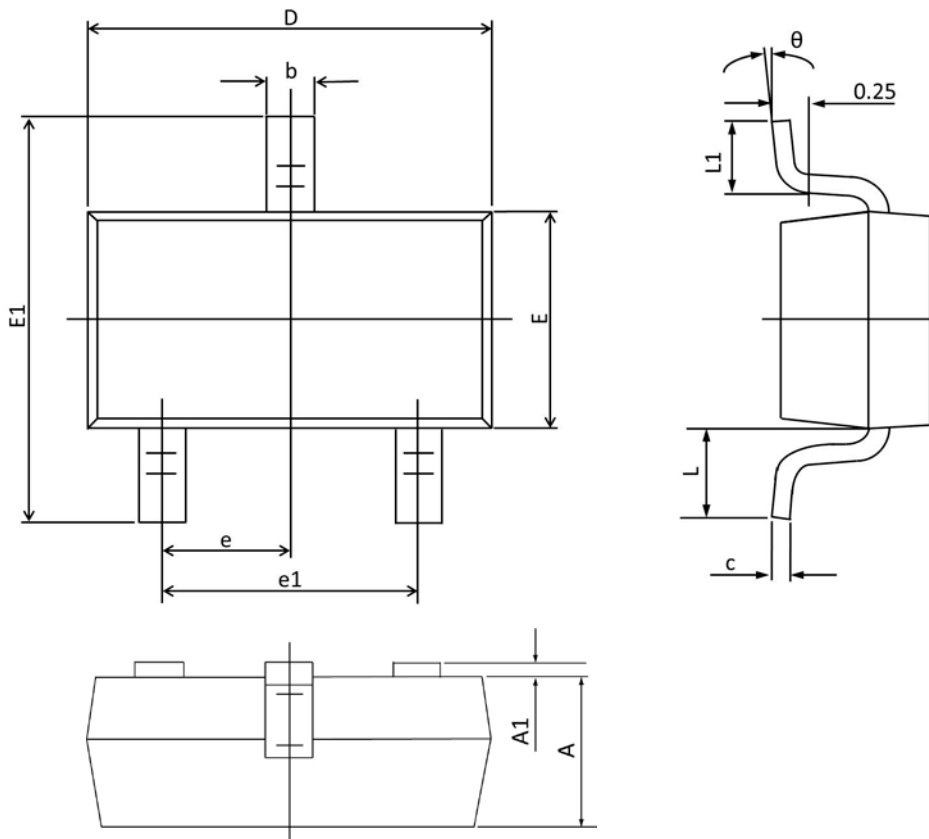


Fig.10 EAS Waveform

SOT23 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°